

PATENT APPLICATION
Docket No.: 9903-071
Client Ref. No.: S02US035

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Jin-Hyuk LEE, et al.

Serial No.: 10/690,782 Examiner: Graybill, David E.

Filed: October 21, 2003 Group Art Unit: 2822

Confirmation No.: 5611

For: METHOD FOR MANUFACTURING A WAFER LEVEL CHIP SCALE PACKAGE

Date: September 5, 2006

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT

Responsive to the Office Action, Paper No. 20060608, dated June 14, 2006, please amend the application as follows.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 7 of this paper.